# 298D

Vishay Sprague



# Solid Tantalum Chip Capacitors MICROTAN<sup>™</sup> Lead Frameless Molded

#### FEATURES

- 0805 and 0603 Footprint
- Lead (Pb)-free face-down terminations
- 8 mm tape and reel packaging available per EIA-481-1 and reeling per IEC 286-3 7" [178 mm] standard



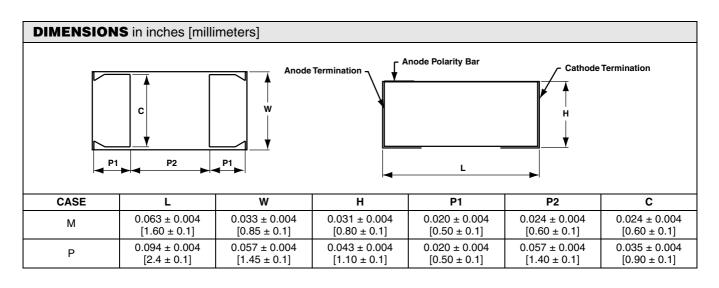
#### **PERFORMANCE CHARACTERISTICS**

**Operating Temperature:** - 55 °C to + 85 °C (To + 125 °C voltage derating)

Capacitance Range: 1  $\mu$ F to 220  $\mu$ F Capacitance Tolerance: ± 20 % standard Voltage Range: 2.5 WVDC to 25 WVDC

298D	106	X0	010	М	2	т
MODEL	CAPACITANCE	CAPACITANCE	DC VOLTAGE RATING	CASE CODE	TERMINATION	REEL SIZE AND
		TOLERANCE	AT + 85 °C I			PACKAGING
	This is expressed in picofarads. The first two digits are the significant figures. The third is the number of zeros to follow.	<b>X0 = ± 20 %</b> X9 = ± 10 %	This is expressed in volts. To complete the three-digit block, zeros precede the voltage rating. A decimal point is indicated by an "R" (6R3 = 6.3 V).	and Case Codes Table	<b>2 = 100 % Tin</b> 4 = Gold Plated	T = Tape and Reel 7" [178 mm] Reel

We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size. Voltage substitutions will be marked with the higher voltage rating.



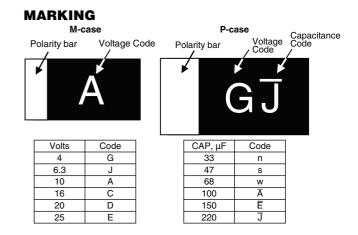


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RATINGS AND CASE CODES						
μF	2.5 V	4 V	6.3 V	10 V	16 V	25 V
1.0					М	М
2.2			М	М	М	
3.3						
4.7			М	М	М	Р
6.8						
10		М	М	М		
15				М		
22		М	М			
33		М	М	P*		
47	М	М	P*	Р		
100	M*	P*	P*			
220	Р	Р				



Note:

\* Preliminary values, contact factory for availability.

#### STANDARD RATINGS

CAPACITANCE (µF)	CASE CODE	PART NUMBER	MAX DC LEAKAGE AT + 25 °C (μΑ)	MAX DF AT + 25 °C (%)	MAX ESR AT + 25 °C 100 kHz (Ω)	MAX RIPPLE 100 kHz I <sub>rms</sub> (A)	∆C/C* (%)
		2.5 WVDC AT + 85 °C, S	URGE = 3.3 V	. 1.6 WVDC AT	+ 125 °C, SURGE	E = 2.1 V	
47	М	298D476X02R5M2T	2.4	20	4.0	0.08	± 30
100	М	298D107X02R5M2T	25.0	40	2.5	0.100	± 30
220	Р	298D227X02R5P2T	11.0	30	3.0	0.122	± 30
		4 WVDC AT + 85 °C, SL	JRGE = 5.2 V	2.7 WVDC AT +	125 °C, SURGE	= 3.4 V	
10	М	298D106X0004M2T	0.5	8.0	3.0	0.09	± 10
22	М	298D226X0004M2T	0.9	15	4.0	0.08	± 15
33	М	298D336X0004M2T	2.6	15	4.0	0.08	± 20
47	М	298D476X0004M2T	3.8	20	4.0	0.08	± 30
100	Р	298D107X0004P2T	4.0	20	2.0	0.1	± 30
220	Р	298D227X0004P2T	17.6	30	3.0	0.122	± 30
		6.3 WVDC AT + 85 °C	, SURGE = 8 V.	4 WVDC AT +	125 °C, SURGE	= 5 V	
2.2	М	298D225X06R3M2T	0.5	10	5.0	0.07	± 10
4.7	М	298D475X06R3M2T	0.5	8.0	3.0	0.09	± 10
10	М	298D106X06R3M2T	0.6	8.0	3.0	0.09	± 10
22	М	298D226X06R3M2T	2.8	15	4.0	0.08	± 15
33	М	298D336X06R3M2T	4.2	20	4.0	0.08	± 30
47	Р	298D476X06R3P2T	3.0	22	3.0	0.122	± 20
100	Р	298D107X06R3P2T	6.3	20	2.0	0.150	± 20
		10 WVDC AT + 85 °C,	SURGE = 13 V.	7 WVDC AT +	- 125 °C, SURGE	= 8 V	
2.2	М	298D225X0010M2T	0.5	10	10	0.05	± 10
4.7	М	298D475X0010M2T	0.5	6.0	4.0	0.08	± 15
10	М	298D106X0010M2T	1.0	8.0	4.0	0.08	± 15
15	М	298D156X0010M2T	1.5	12	4.0	0.08	± 20
33	Р	298D336X0010P2T	3.3	10	2.0	0.150	± 10
47	Р	298D476X0010P2T	4.7	22	3.0	0.122	± 20
		16 WVDC AT + 85 °C, S	SURGE = 20 V	. 10 WVDC AT +	- 125 °C, SURGE	= 12 V	
1.0	М	298D105X0016M2T	0.5	6.0	12.0	0.045	± 15
2.2	Μ	298D225X0016M2T	0.5	10	12.0	0.045	± 15
4.7	М	298D475X0016M2T	0.8	8.0	6.0	0.06	± 15
		25 WVDC AT + 85 °C, S	SURGE = 32 V	. 17 WVDC AT +	- 125 °C, SURGE	= 20 V	
1.0	М	298D105X0025M2T	0.5	6.0	10.0	0.05	± 10
4.7	Р	298D475X0025P2T	1.2	6.0	4.0	0.106	± 10

Note

\* See Performance Characteristics tables, page 41.



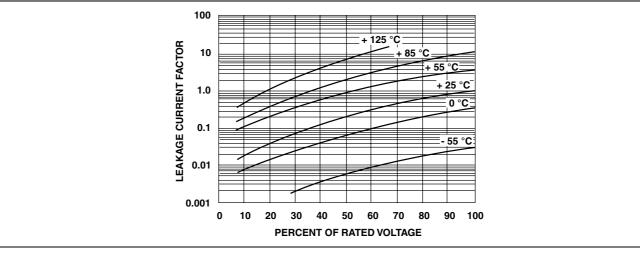
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#### CAPACITORS PERFORMANCE CHARACTERISTICS

ELECTRICAL PERFO	RMANCE CHARAC	<b>TERISTICS</b>				
ITEM	PERFORMANCE CHARACTERISTICS					
Category Temperature Range	- 55 °C to + 85 °C (to + 125 °C with voltage derating)					
Capacitance Tolerance	± 20 %, ± 10 % (at 120 Hz) 2 V <sub>rms</sub> at + 25 °C using a capacitance bridge					
Dissipation Factor (at 120 Hz)	Limits per Standard Rating	s Table. Tested via bridge r	nethod, at 25 °C, 120 Hz.			
ESR (100 kHz)	Limits per Standard Rating	s Table. Tested via bridge r	method, at 25 °C, 100 kHz.			
Leakage Current		the capacitor under test, le	s for 5 minutes using a stead akage current at 25 °C is not r.			
Reverse Voltage	5 % of the DC rating at + 8	5 °C	in the reverse direction eque e application of reverse volta			
Temperature Derating	If capacitors are to be used at temperatures above + 25 °C, the permissible rms ripple current or voltage 1.0 at + 25 °C 0.9 at + 85 °C 0.4 at + 125 °C					
Maximum Permissible Power Dissipation at 25 °C (W) in free air	M-Case: 0.025 P-Case: 0.045					
Operating Temperature	+ 85 °C	5 °C RATING + 125 °C RATING				
	WORKING VOLTAGE	SURGE VOLTAGE	WORKING VOLTAGE	SURGE VOLTAGE		
	4	5.2	2.7	3.4		
	6.3	8	4	5		
	10	13	7	8		
	16	20	10	12		
	20	26	13	16		
	25	32	17	20		
	35	46	23	28		
	50	65	33	40		

#### **TYPICAL LEAKAGE CURRENT FACTOR RANGE**



#### Notes

- $\bullet$  At + 25 °C, the leakage current shall not exceed the value listed in the Standard Ratings Table.
- $\bullet$  At + 85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings Table.
- At + 125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings Table



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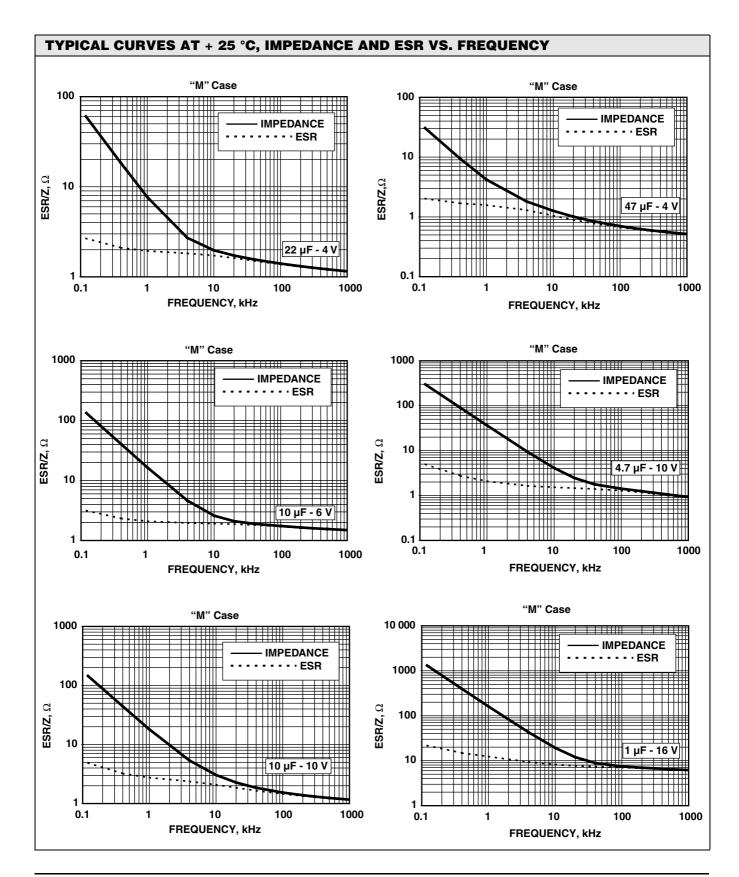
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ENVIRONMENTAL PERFORMANCE CHARACTERISTICS					
ITEM	CONDITION	POST TEST PERFORMANCE			
Life Test at + 85 °C	1000 h application of rated voltage at 85 °C with a 3 $\Omega$ series resistance, MIL-STD 202G Method 108A	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Not to exceed 150 % of initial Not to exceed 200 % of initial		
Humidity Tests	At 40 °C/90 % RH 500 h, no voltage applied. MIL-STD 202G Method 103B	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Not to exceed 150 % of initial Not to exceed 200 % of initial		
Thermal Shock	At - 55 °C/+ 125 °C, 30 min. each, for 5 cycles. MIL-STD 202G Method 107G	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Not to exceed 150 % of initial Not to exceed 200 % of initial		

TEST CONDITION	CONDITION	POST TEST PERFORMANCE		
Terminal Strength	Apply a pressure load of 5 N for $10 \pm 1$ s horizontally to the center of capacitor side body. AECQ-200 rev. C Method 006	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Initial specified value or less Initial specified value or less	
		There shall be no mechanical or visual damage to capacito post-conditioning.		
Substrate Bending (Board flex)	With parts soldered onto substrate test board, apply force to the test board for a deflection of 1 mm. AECQ-200 rev. C Method 005	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Initial specified value or less Initial specified value or less	
Vibration	MIL-STD-202G, Method 204D, 10 Hz to 2000 Hz, 20 G Peak	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Initial specified value or less Initial specified value or less	
		There shall be no mechanical or visual damage to capacitor post-conditioning.		
Shock	Mil-Std-202G, Method 213B, Condition I, 100G Peak	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Initial specified value or less Initial specified value or less	
		There shall be no mech post-conditioning.	nanical or visual damage to capacitors	
Resistance to Solder Heat	At 260 °C, for 10 seconds, reflow	Capacitance Change Dissipation Factor Leakage Current	Refer to Standard Ratings Table Not to exceed 150 % of initial Not to exceed 200 % of initial	
		There shall be no mechanical or visual damage to capacitors post-conditioning.		
Solderability	MIL-STD-202G, Method 208H, ANSI/J-Std-002, Test B. Applies only to Solder and tin plated terminations. Does not apply to gold terminations.	There shall be no mechanical or visual damage to capacitors post-conditioning.		
Resistance to Solvents	MIL-STD-202, Method 215D	There shall be no mech post-conditioning.	nanical or visual damage to capacitors	
Flammability	Encapsulation materials meet UL94 VO with an oxygen index of 32 %.			

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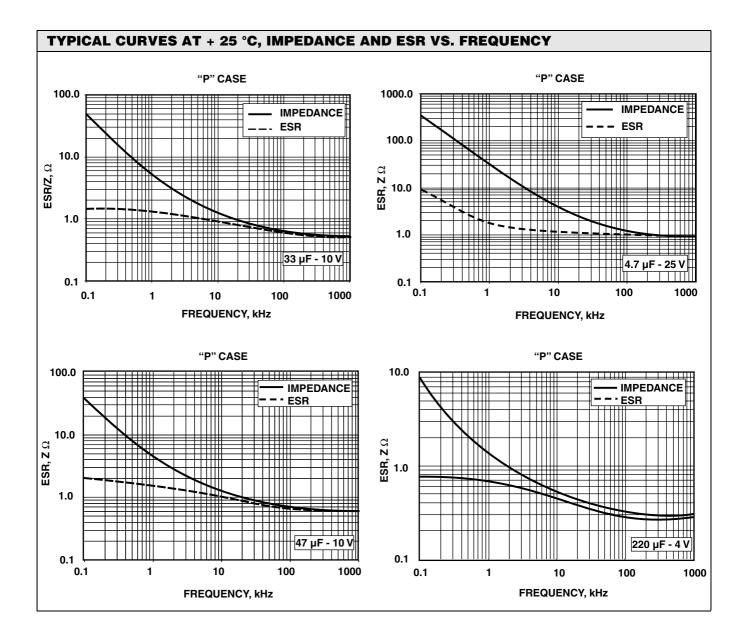
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